

REMARKS

Claims 1-7, 15-23, 28, 30 and 33-42 are pending. By this Amendment, claims 39-42 are added, claims 29, 31 and 32 are cancelled, and claims 1, 3, 16, 19, 20, 28, 33, 35 and 37 are amended. The claims are amended to even more clearly distinguish over the applied references. No new matter is added by the above amendments.

I. August 20, 2003 Information Disclosure Statement

An Information Disclosure Statement (IDS) was filed on August 20, 2003. The Examiner is requested to consider the information forwarded with the IDS.

II. All Claims are Patentable

Applicant notes with appreciation the identification of allowable subject matter in claims 4 and 5. Applicant respectfully submits that all pending claims are in condition for allowance for at least the reasons set forth below.

Claims 28, 29, 31 and 32 stand rejected under 35 U.S.C. §112, second paragraph. This rejection has been overcome by the above amendments to the claims.

Claim 1 stands rejected under 35 U.S.C. §102(b) over JP-A-5-235060 (Sakurai). This rejection is respectfully traversed.

Sakurai discloses that a semiconductor integrated circuit substrate 1 is secured by an adhesive 3 to three rubber-like elastic bodies 7 arranged at vertices of a triangle on a supporting substrate 5 in a post-process of a wafer-scale integration. Sakurai only discloses that the semiconductor integrated circuit substrate 1 is secured to the supporting substrate 5, and fails to disclose or suggest a substrate holding apparatus that is used in an exposure apparatus and which supports a substrate by a plurality of support members that contact a surface of the substrate that is different from a sensitive surface thereof exposed by an exposure beam. In addition, Sakurai does not disclose or suggest that a protrusion is disposed

on a base member in a substantially same shape as an outside shape of a substrate, and that a plurality of supporting members are disposed like a triangular lattice inside of the protrusion.

Accordingly, claim 1 is patentable over Sakurai. Withdrawal of the rejection is requested.

Claims 1-3, 6, 7, 15-23 and 28-38 stand rejected under 35 U.S.C. §103(a) over U.S. Patent No. 5,191,218 to Mori et al. in view of Sakurai. This rejection is respectfully traversed.

Mori et al. discloses a wafer holding device in which two ring-like grooves 9₁ and 9₂ are formed on an attracting surface 2 of a holding base 1. Mori et al only discloses the wafer holding device, and fails to disclose or suggest that: (1) that a protrusion is disposed on a base member or a holder having a low thermal expansion coefficient in a substantially same shape as an outside shape of a substrate, and (2) a plurality of supporting members disposed like a triangular lattice inside of the protrusion. Sakurai fails to provide the deficiencies in Mori et al. noted above.

Accordingly, the claims are patentable over Mori et al. in view of Sakurai. Withdrawal of the rejection is requested.

Claims 1-3, 6, 7, 15-23 and 28-38 stand rejected under 35 U.S.C. §103(a) over U.S. Patent No. 4,666,291 to Taniguchi et al. in view of Sakurai. This rejection is respectfully traversed.

Taniguchi et al. discloses a chuck platen 12 having a top surface 12A on which a wafer 6 is disposed, and a bottom surface 12B in which slits 15 are formed. Taniguchi et al. only discloses the chuck platen, and fails to disclose or suggest: (1) that a protrusion is disposed on a base member or a holder having a low thermal expansion coefficient in a substantially same shape as an outside shape of a substrate, and (2) a plurality of supporting members are

disposed like a triangular lattice inside of the protrusion. Sakurai fails to provide the deficiencies in Taniguchi et al.

Accordingly, the claims are patentable over Taniguchi et al. and Sakurai. Withdrawal of the rejection is requested.

Claims 1-3, 6, 7, 15-23 and 28-38 stand rejected under 35 U.S.C. §103(a) over JP-A-9-295236 (Hashimoto) in view of U.S. Patent No. 6,072,163 to Armstrong et al. This rejection is respectfully traversed.

Hashimoto discloses a suction holding apparatus having a plurality of elevating pins 6 disposed in the shape of a circle. Armstrong et al. discloses a bake/chill apparatus having a trio of lift pin shafts 427 arranged in triangular fashion at 120° intervals around lift pin base 426. Hashimoto and Armstrong et al. fail to disclose a substrate holding apparatus which is used in an exposure apparatus and which supports a substrate by a plurality of support members that contact a surface of the substrate that is different from a sensitive surface thereof that is exposed by an exposure beam. The references also fail to disclose or suggest: (1) that a protrusion is disposed on a base member or a holder having a low thermal expansion coefficient in a substantially same shape as an outside shape of a substrate, and (2) a plurality of supporting members disposed like a triangular lattice inside of the protrusion.

Accordingly, the claims are patentable over Hashimoto and Armstrong et al. Withdrawal of the rejection is requested.

III. Conclusion

In view of the foregoing, Applicant respectfully submits that this application is in condition for allowance. Favorable reconsideration and prompt allowance are earnestly solicited.

Should the Examiner believe that anything further would be desirable to place this application in even better condition for allowance, the Examiner is invited to contact Applicant's undersigned attorney at the telephone number listed below.

Respectfully submitted,



Mario A. Costantino
Registration No. 33,565

MAC/ccs

Attachments:

Amendment Transmittal
Petition for Extension of Time

Date: October 23, 2003

OLIFF & BERRIDGE, PLC
P.O. Box 19928
Alexandria, Virginia 22320
Telephone: (703) 836-6400

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